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TITLE: ELECTRICALLY CONDUCTIVE RESIN PASTE

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ABSTRACT:

PURPOSE: To provide an electrically conductive resin paste composed of respective specific epoxy compound, hydroxyl-containing compound and silver powder at specific ratios, having excellent coating workability and low water-absorption, providing a cured product having low elastic modulus and free from cracking and useful for bonding a semiconductor element to a metal frame, etc.

CONSTITUTION: This electrically conductive resin paste contains, as essential components, (A) 60-85wt.% of silver powder, (B) 3-20wt.% of an epoxy compound having naphthalene skeleton and expressed by the formula I (R<SB>1</SB> and R<SB>2</SB> are glycidyl ether group or H and at least one of R<SB>1</SB> and R<SB>2</SB> is glycidyl ether group; (n) is 0 or 1), e.g 1,6-dihydroxynaphthalene diglycidyl ether and (C) 0.1-20wt.% of a compound

having two phenolic hydroxyl groups in one molecule.

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